

Laminated plate for printed circuit plate - has surface layer of glass woven cloth impregnated with thermosetting resin and contg. inorganic filler

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Patent Family:

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JP 6112611	A	19940422	JP 92260030	A	19920929	199421 B
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Patent Details:

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Abstract (Basic): JP 6112611 A

Laminated plate has a surface layer made of a glass woven cloth impregnated with a thermosetting resin and contains 10-200 wt.%, w.r.t. the resin in the surface layer, of inorganic filler.

The filler is e.g. Al hydroxide, silica, talc or clay. The thermosetting resin is e.g. polyimide resin, epoxy resin, unsatd. polyester resin or phenol resin.

USE/ADVANTAGE - The laminated plate is used for electric equipment, electronic equipment, communication machine, etc. The laminated plate has good tracking resistance without inhibiting electrical characteristics, etc.

In an example, 100 pts.wt., based on the resin content, of epoxy resin varnish was mixed with 50 pts.wt. Al hydroxide and 2 pts.wt. ultrafine powdery silica. A glass woven cloth was impregnated with the obtd. varnish to obtain prepreg (A) contg. 30-40 wt.% resin. Glass cloth was impregnated with the epoxy resin varnish to obtain prepreg (B) contg. 40-50 wt.% of resin. Six sheets of prepreg (B) were placed each other and prepreps (A) were placed on both sides of the laminated prepreps (B). Cu foil of 18 microns thick was placed on prepreg (B) and the laminate was pressed at 165 deg.C at 60 kg/cm² for 90 min. to obtain a Cu-lined laminate of 1.67 mm thick.

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Title Terms: LAMINATE; PLATE; PRINT; CIRCUIT; PLATE; SURFACE; LAYER; GLASS; WOVEN; CLOTH; IMPREGNATE; THERMOSETTING; RESIN; CONTAIN; INORGANIC; FILL

Derwent Class: A23; A85; L03; P73; V04

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